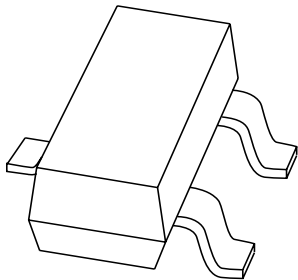


# DATA SHEET



## **BC856; BC857; BC858** PNP general purpose transistors

Product data sheet  
Supersedes data of 2003 Apr 09

2004 Jan 16

# PNP general purpose transistors

# BC856; BC857; BC858

### FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 65 V).

### APPLICATIONS

- General purpose switching and amplification.

### DESCRIPTION

PNP transistor in a SOT23 plastic package.  
 NPN complements: BC846, BC847 and BC848.

### MARKING

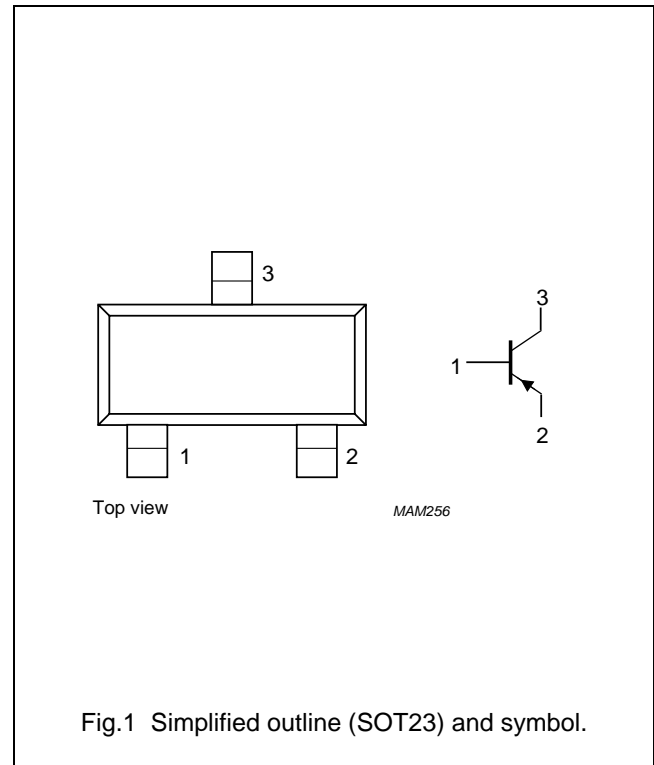
TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BC856	3D*
BC856A	3A*
BC856B	3B*
BC857	3H*
BC857A	3E*
BC857B	3F*
BC857C	3G*
BC858B	3K*

### Note

- \* = p: made in Hong Kong.  
 \* = t: made in Malaysia.  
 \* = W: made in China.

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BC856	–	plastic surface mounted package; 3 leads	SOT23
BC857	–	plastic surface mounted package; 3 leads	SOT23
BC858	–	plastic surface mounted package; 3 leads	SOT23

## PNP general purpose transistors

## BC856; BC857; BC858

**LIMITING VALUES**

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	BC856		–	–80	V
	BC857		–	–50	V
	BC858		–	–30	V
V <sub>CEO</sub>	collector-emitter voltage	open base			
	BC856		–	–65	V
	BC857		–	–45	V
	BC858		–	–30	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	–5	V
I <sub>C</sub>	collector current (DC)		–	–100	mA
I <sub>CM</sub>	peak collector current		–	–200	mA
I <sub>BM</sub>	peak base current		–	–200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	–	250	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C
T <sub>amb</sub>	operating ambient temperature		–65	+150	°C

**Note**

1. Transistor mounted on an FR4 printed-circuit board, standard footprint.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air; note 1	500	K/W

**Note**

1. Transistor mounted on an FR4 printed-circuit board, standard footprint.

## PNP general purpose transistors

## BC856; BC857; BC858

**CHARACTERISTICS**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

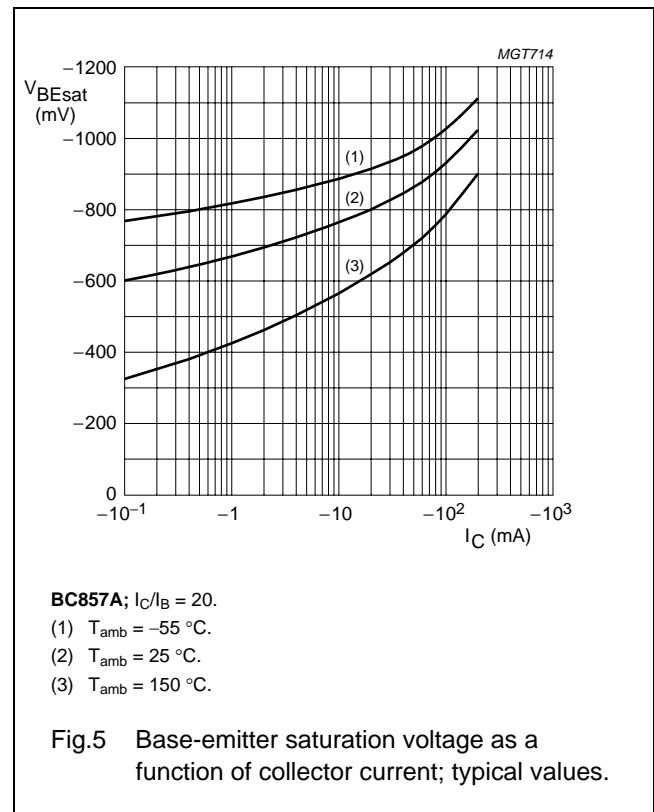
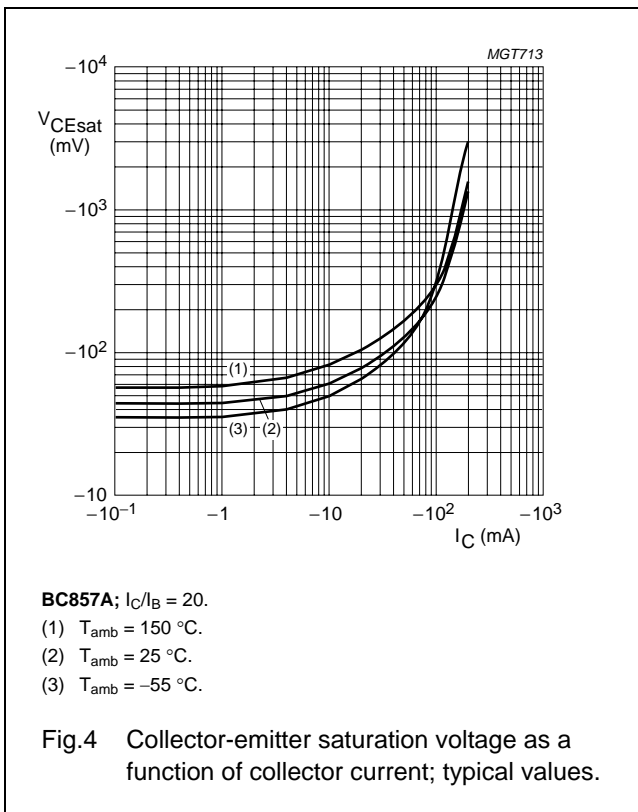
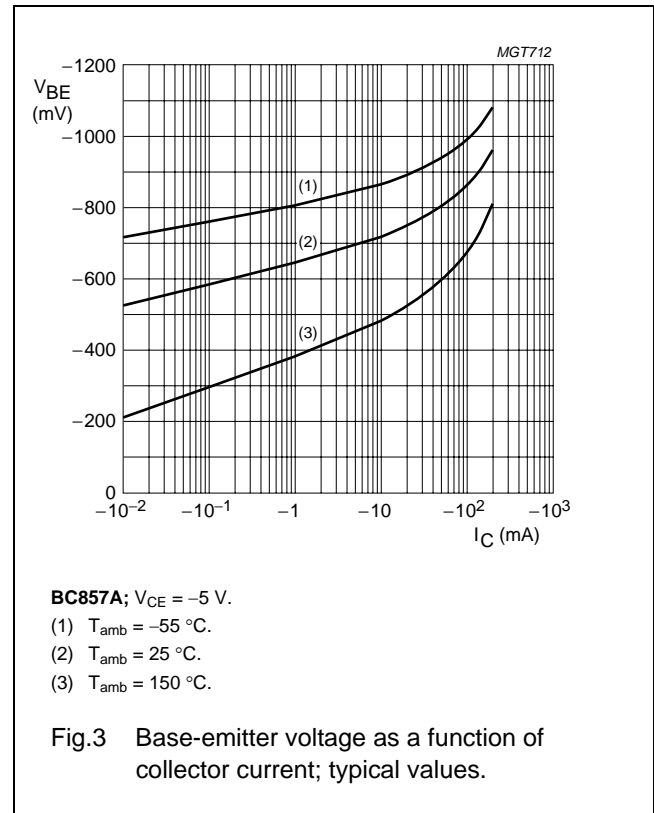
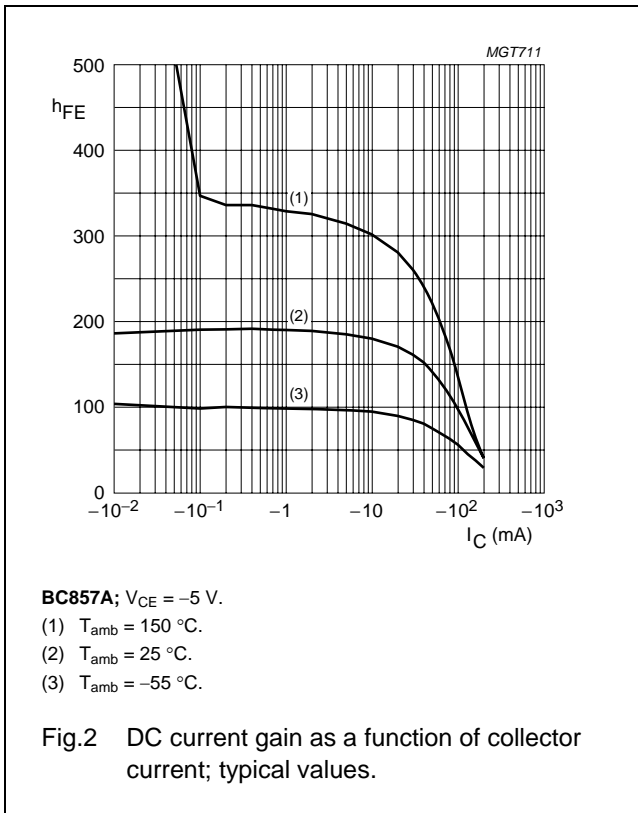
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT				
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0$	–	–1	–15	nA				
		$V_{CB} = -30\text{ V}; I_E = 0;$ $T_j = 150\text{ °C}$	–	–	–4	$\mu\text{A}$				
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0$	–	–	–100	nA				
$h_{FE}$	DC current gain	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$								
							BC856	125	–	475
							BC857	125	–	800
							BC856A; BC857A	125	–	250
							BC856B; BC857B; BC858B	220	–	475
BC857C	420	–	800							
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	–	–75	–300	mV				
		$I_C = -100\text{ mA}; I_B = -5\text{ mA};$ note 1	–	–250	–650	mV				
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	–	–700	–	mV				
		$I_C = -100\text{ mA}; I_B = -5\text{ mA};$ note 1	–	–850	–	mV				
$V_{BE}$	base-emitter voltage	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$	–600	–650	–750	mV				
		$I_C = -10\text{ mA}; V_{CE} = -5\text{ V}$	–	–	–820	mV				
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_e = 0;$ $f = 1\text{ MHz}$	–	4.5	–	pF				
$f_T$	transition frequency	$V_{CE} = -5\text{ V}; I_C = -10\text{ mA};$ $f = 100\text{ MHz}$	100	–	–	MHz				
F	noise figure	$I_C = -200\text{ }\mu\text{A}; V_{CE} = -5\text{ V};$ $R_S = 2\text{ k}\Omega; f = 1\text{ kHz};$ $B = 200\text{ Hz}$	–	2	10	dB				

**Note**

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

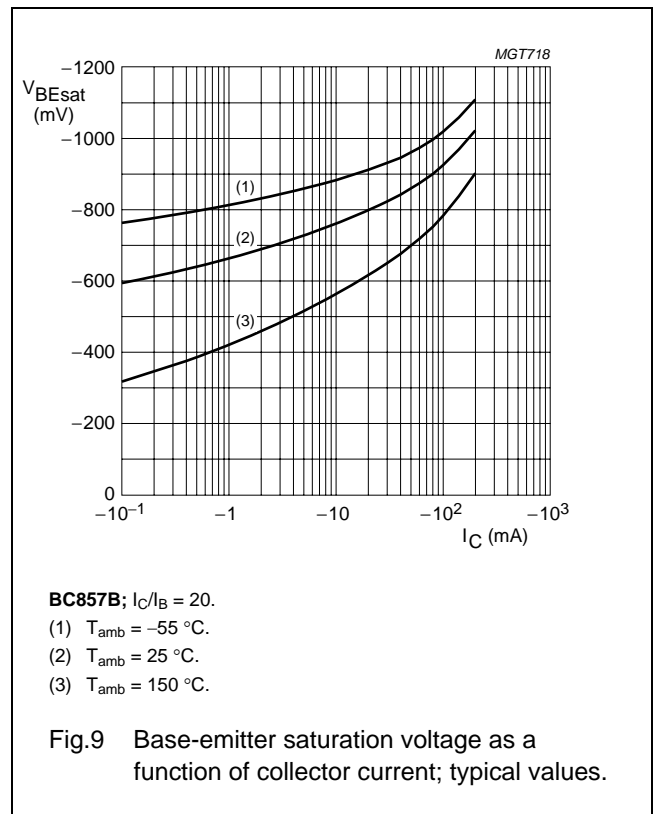
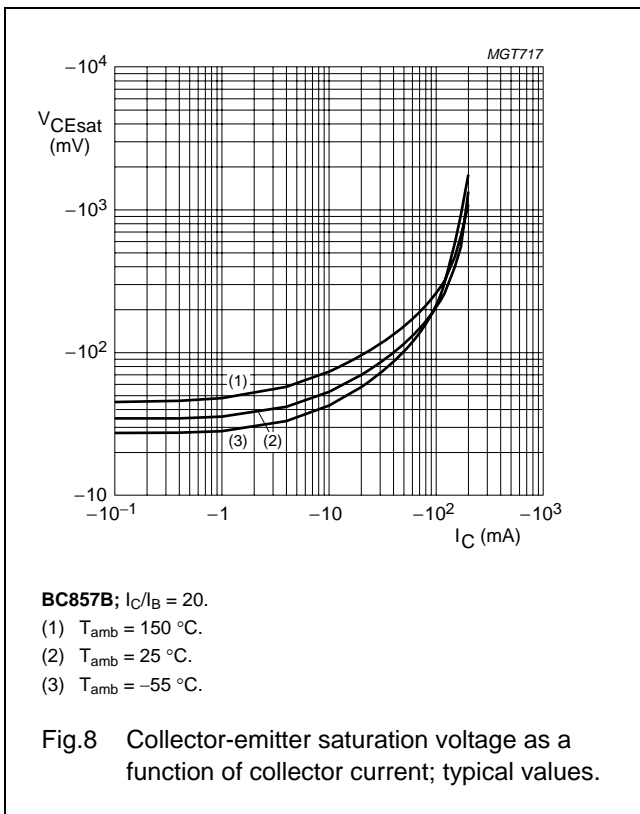
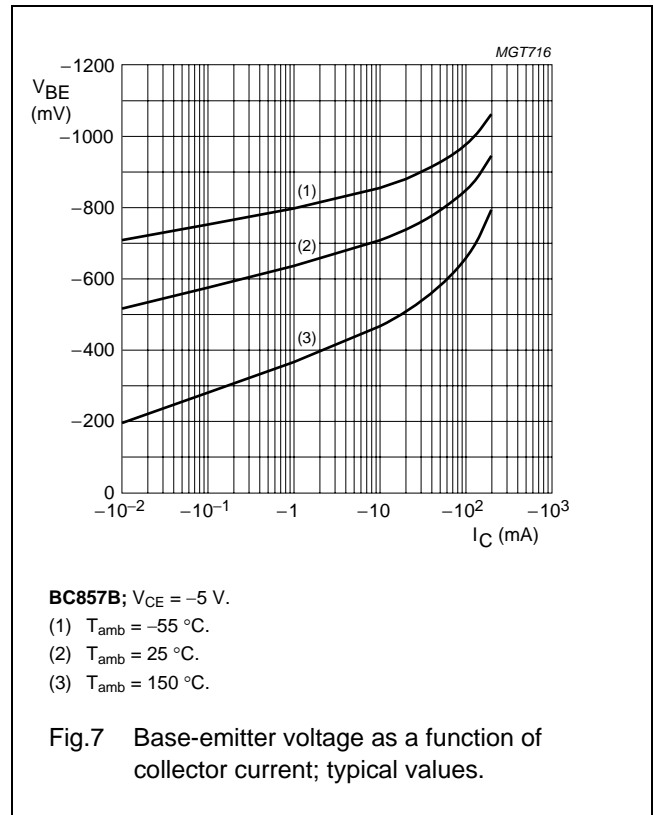
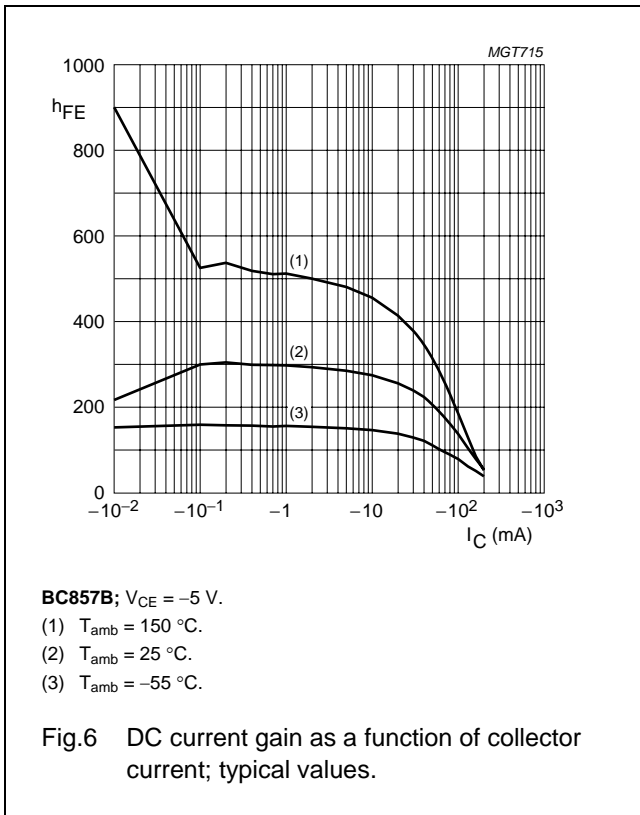
PNP general purpose transistors

BC856; BC857; BC858



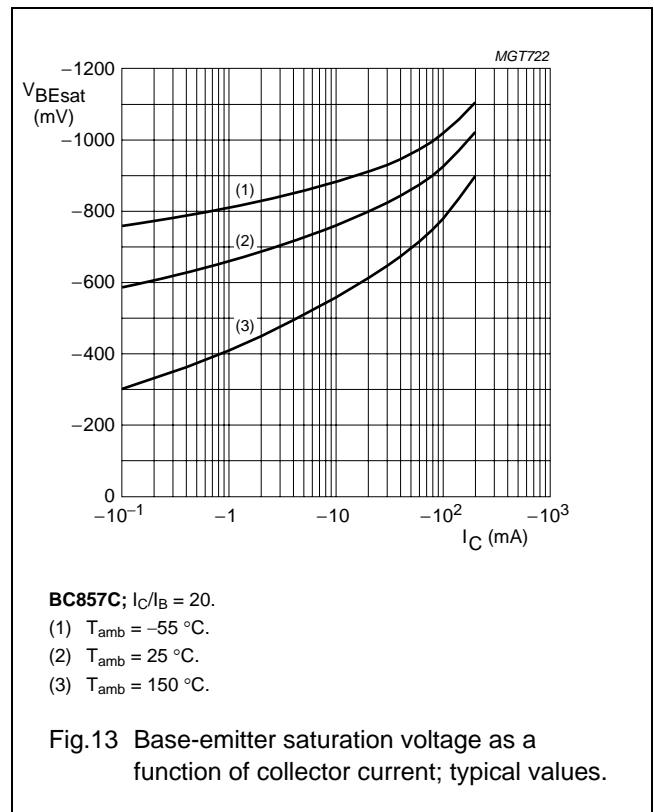
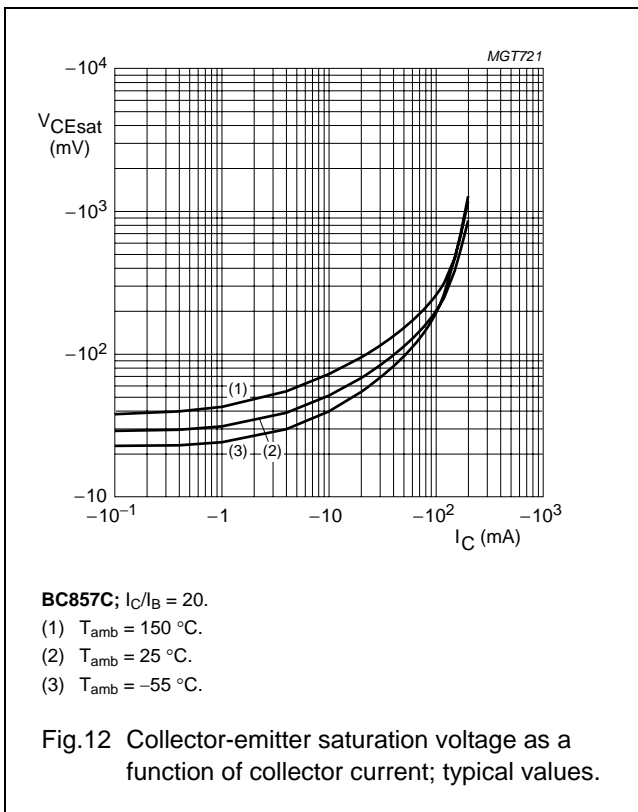
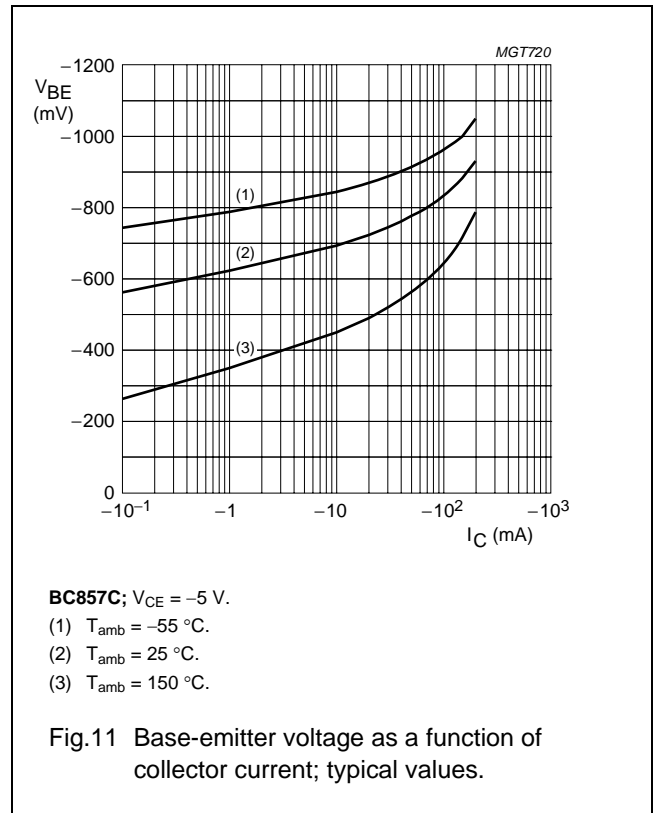
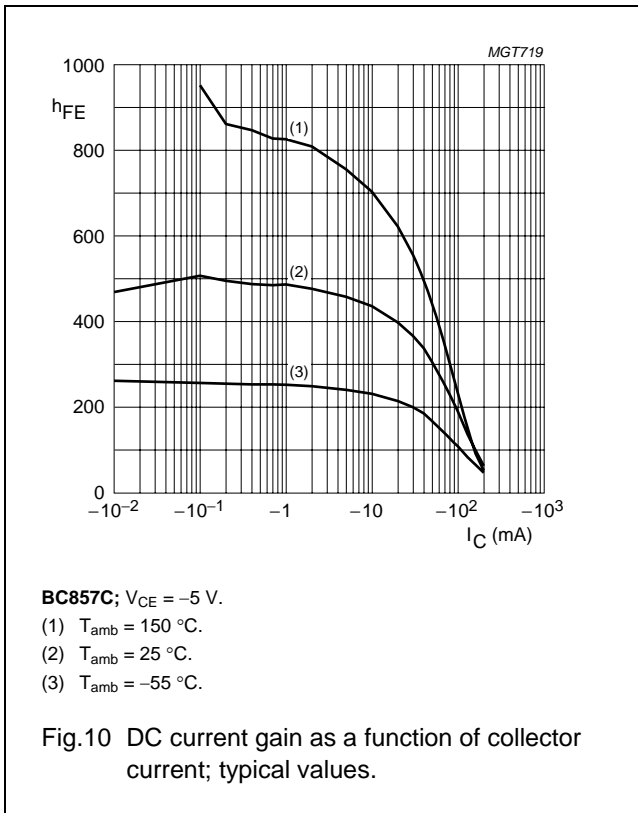
PNP general purpose transistors

BC856; BC857; BC858



PNP general purpose transistors

BC856; BC857; BC858



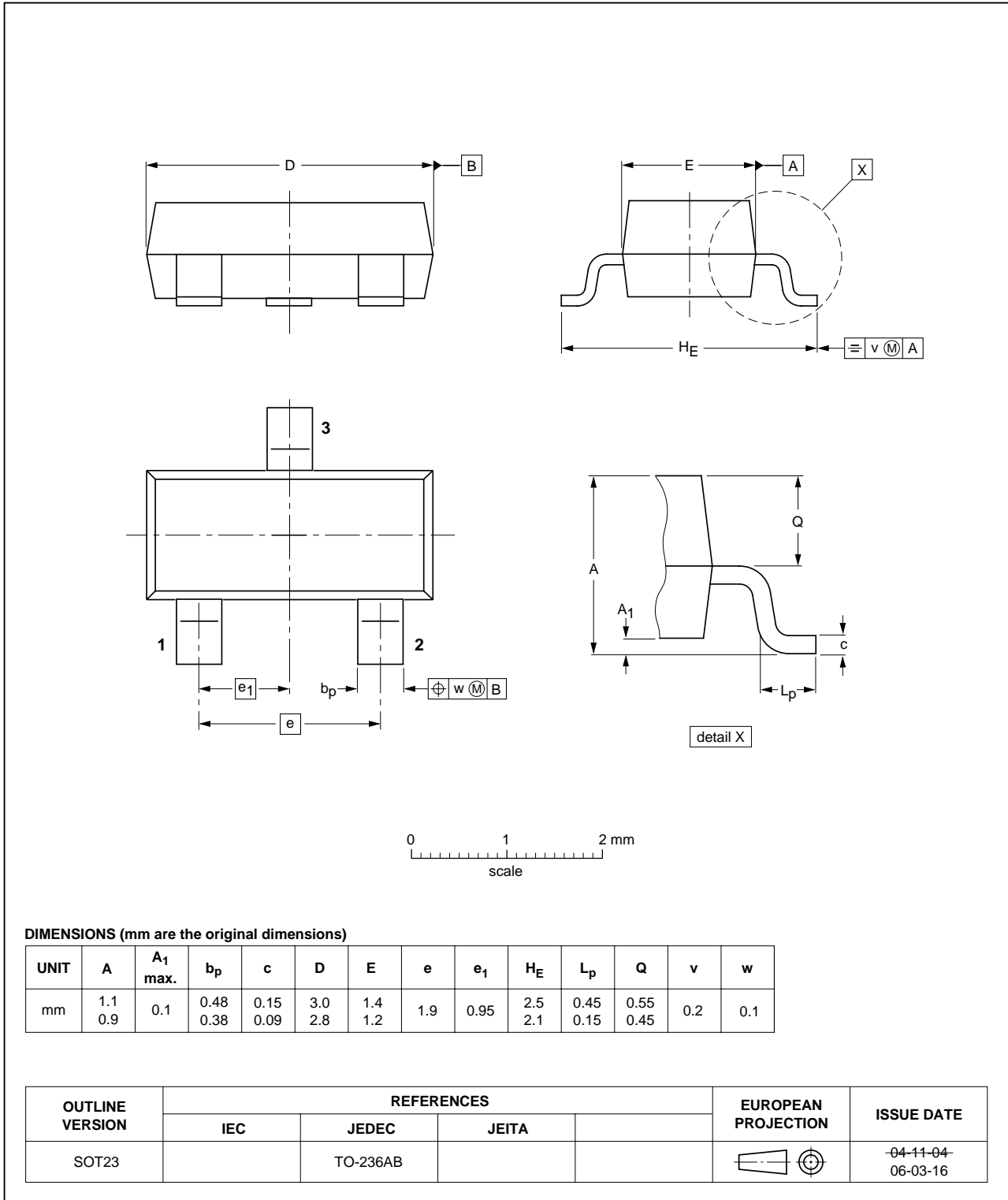
PNP general purpose transistors

BC856; BC857; BC858

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23





PNP general purpose transistors

BC856; BC857; BC858

**DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# ***NXP Semiconductors***

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## **Contact information**

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